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1940 DUKE S' ALEXANDRI	STREET IA, VA 22314		MCDONALD, RODNEY GLENN	
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Please find below and/or attached an Office communication concerning this application or proceeding.

RG

Office Action Summary

Application No. 09/926,041

Applicant(s)

Sato et al.

Examiner

Rodney McDonald

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The MAILING DATE of this communication appears on the cover sheet with the correspondence address									
	or Reply		_						
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. • Extensions of time may be available under the provisions of 37 CFR 1.136 (a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the									
mailing date of this communication. If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. If NO period for reply is specified above, the maximum statutory period will epply and will expire SIX (6) MONTHS from the mailing date of this communication. Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Amy reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).									
Status									
1) 💢	Responsive to communication(s) filed on Jan 29, 20	003		· .					
2a) 💢	This action is FINAL . 2b) This action is non-final.								
3) 🗆	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11; 453 O.G. 213.								
Disposition of Claims									
4) 🗶	Claim(s) <u>1-27</u>			is/are pending in the application.					
4	a) Of the above, claim(s)		····	is/are withdrawn from consideration.					
5) 🗆	Claim(s)			is/are allowed.					
6) 💢	Claim(s) <u>1-27</u>			is/are rejected.					
7) 🗆	Claim(s)								
8) 🗌	Claims								
	tion Papers								
9) 🗆	The specification is objected to by the Examiner.			`					
10)	10) ☐ The drawing(s) filed on is/are a) ☐ accepted or b) ☐ objected to by the Examiner.								
	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).								
11)	The proposed drawing correction filed on								
	If approved, corrected drawings are required in reply to								
12)	The oath or declaration is objected to by the Examir	ner.							
Priority under 35 U.S.C. §§ 119 and 120									
13)💢	13) Acknowledgement is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).								
a) 🕽	⟨ All b) □ Some* c) □ None of:								
	1. X Certified copies of the priority documents have	e been receive	d.						
	2. Certified copies of the priority documents have	e been receive	d in App	olication No					
	3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).								
	ee the attached detailed Office action for a list of the								
	14) Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).								
_	a) The translation of the foreign language provisional application has been received.								
15) Acknowledgement is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.									
Attachm	nent(s) otice of References Cited (PTO-892)	4) Interview Su	immary (PT	0-413) Paper No(s)					
	otice of Draftsperson's Patent Drawing Review (PTO-948)	_		nt Application (PTO-152)					
	formation Disclosure Statement(s) (PTO-1449) Paper No(s).	6) Other:							

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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103© and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

2. Claim 1 is rejected under 35 U.S.C. 103(a) as being unpatentable over Kazuyoshi et al. (Japan 11-345780).

Kazuyoshi et al. teach a surface part of a vacuum deposition apparatus that has a range of ten-point means roughness (Rz) of 5 to 200 microns and a range of a mean interval S of local ridges of 5 to 100 microns. (See Abstract) This prevents film peeling within a reaction container during deposition film formation. (See Machine translation [0006]) One can calculate the Rz value from the formula in Figure 4 by JIS B 0601. One can calculate the S value from the formula

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in Figure 5. (See Machine translation [0016]) As the film formed on the surface part a metallic material such as aluminum, Cr, Mo, Au, In, nickel, Ti, Pt, Fe(s) and these alloys can be used. The method for forming this raise film can be the plasma metal spray method. (See Machine translation [0023])

The differences between Kazuyoshi et al. and the present claim is that the Rv and Rp values are not taught.

Since the Rz value is between 5 to 200 microns the Rv and Rp values fall within Applicant's claimed range. The Rv and Rp values are seen in Figure 4 as Yp and Yv values. (See Figure 4)

The motivation for utilizing a film of a certain roughness value is that it allows for preventing film from peeling from the reaction container during deposition film formation. (See Abstract)

Therefore, it would have been obvious to coat a component with a film of a certain roughness value as taught by Kazuyoshi et al. because it prevents the film from peeling from the reaction container during deposition film formation.

3. Claims 1-4, 6-14, 14, and 27 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kazuyoshi et al. (Japan 11-345780; Machine translation) in view of Michio et al. (U.S. Pat. 09-272965; Machine translation).

Kazuyoshi et al. is discussed above and all as applies above. (See Kazuyoshi et al. discussed above)

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The differences between Kazuyoshi et al. and the present claims is that the thermal expansion coefficient of the film layer is not discussed, where two or more layers are utilized is not discussed, the Vicker hardness of the coating is not discussed and the thickness of the coating is not discussed.

Michio et al. teach parts 1 for a vacuum film forming device has the main body 2 of the parts and sprayed film 3 formed on the surface of the main body 2. The vacuum film forming device has a holding part for the sample to be film-coated such as a substrate holder arranged in a vacuum vessel, a film forming source such as a target arranged opposite to the holding part for the sample to be film-coated, film forming source holding parts such as a target outer circumference press and a center cap and sticking preventing parts. Among these, at least one selected from among the holding part for the sample to be film-formed, film forming source holding parts and sticking preventing parts is constituted of the above parts for a vacuum film forming device, target and backing plate. (See Abstract)

The thermal sprayed film material has a metallic material with a thermal coefficient below 10*10-6/K. (Machine translation [0020]) The surface roughness of the film is from 5-50 micrometers. The thickness of the film is from 50 to 500 micrometers. (Machine translation [0015])

The thermal spraying film 3 consists not only of the coat by single material but of a material different, for example. The thermal spraying film 3 may consist of coats of more than two-layer. When applying the thermal-spraying film 3 more than two-layer, as for the differential

thermal expansion between tem, it is desirable to carry out to below 10*10-6/K like the differential thermal expansion of the thermal-spraying film 3, and the main part 2 of parts and membrane formation material. (Machine translation [0030])

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Ti thermal spray film can be used. (Machine translation [0044])

The motivation for utilizing a two layer film of specified thickness is that it allows for preventing the generation of defects in wiring films. (See Abstract)

As to the Vickers Hardness since both Kazuyoshi et al. and Michio et al. teach spray coating a metal such as Titanium it is presumed that such spray process would produce a film having the required Vicker hardness since Applicant utilizes spray coating to produce their film. (See Kazuyoshi et al. and Michio et al. discussed above)

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified Kazuyoshi et al. by utilizing a layer comprised of a single or two layers with particular coefficient of thermal expansion and thickness as taught by Michio et al. because it allows for preventing the generation of defects in wiring films.

4. Claims 5, 12, 13 and 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kazuyoshi et al. in view of Michio et al. as applied to claims 1-4, 6 M, 14 M and M above, and further in view of Bang et al. (U.S. Pat. 6,235,120).

The differences not yet discussed is the layers relieving stress.

FIG. 1A is a side elevational view, generally representing a processing chamber part 11, configured in accordance with the present invention. The processing chamber part 11 comprises

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an underlying part 13 having a first CTE, an intermediate coating 15 having an intermediate CTE, and a surface layer 17 having a second CTE. The underlying part 13 exhibits one or more bulk characteristics which are favorable, and one or more surface characteristics which are unfavorable, and the surface layer 17 exhibits at least one surface characteristic which is favorable, and which is unfavorably possessed by the underlying layer 13 (e.g., the underlying part 13 is corrosive in the processing environment and the surface layer 17 is not corrosive in the processing environment). The intermediate coating 15 is comprised of a plurality of intermediate layers 19a-e, as shown in FIG. 1A, each of which has an intermediate CTE. As used herein, an intermediate CTE refers to a CTE value that falls within the range between the CTE value of the underlying part 13 and the CTE value of the surface layer 17. (Column 2 lines 50-68; Column 3 lines 1-9)

FIG. 1B is a side elevational view representing the part of FIG. 1A at an elevated temperature. FIG. 1B is useful for understanding how the inventive processing chamber part 11 reduces the selection criteria for each material layer. (Column 3 lines 16-19)

For example, assume the underlying part 13 has a CTE of 7.times.10.sup.-6/c, and the surface layer 17 has a CTE of 1.times.10.sup.-6/c. The difference in CTE, in this example 6.times.10.sup.-6/c, is proportional to the overall thermal stress that would exist between the underlying part 13 and the surface layer 17 if no intermediate coating 15 existed therebetween. Preferably, to gradually reduce the overall thermal stress, each intermediate layer 19a-e reduces the overall thermal stress by an equivalent amount, in this example by an amount proportional to

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1.times.10.sup.-6/c. To achieve equal thermal stress reduction, intermediate layer 19a has a CTE of 6.times.10.sup.-6/c, intermediate layer 19b has a CTE of 5.times.10.sup.-6/c, intermediate layer 19c has a CTE of 4.times.10.sup.-6/c, intermediate layer 19d has a CTE of times.10.sup.-6/c and intermediate layer 19e has a CTE of 2.times.10.sup.-6/c. Accordingly, during thermal cycling, stress between any two adjacent layers is proportional to 1.times.10.sup.-6/c, 1/6 the stress that would exist in the absence of the intermediate coating 15. (Column 3 lines 20-36)

Moreover, material selection is facilitated, as both the materials of the underlying part, and of the surface layer may be selected for their respective bulk, and surface characteristics, without regard for CTE matching. Thus, the present invention greatly increases the universe of acceptable materials for underlying parts and for surface layers, allowing semiconductor processing chamber parts to be easily tailored to meet the requirements of a given process. Similarly, with use of the present invention, materials for the intermediate layers 19a-e may be freely selected without regard for surface characteristics--the primary consideration for selection of an intermediate layer 19a-e being the desired CTE. (Column 3 lines 53-65)

The processing chamber part 11 represents any number of processing chamber parts (e.g., process kit parts, heaters, chamber walls). For example, the underlying part 13 may be a heating layer (e.g., comprising aluminum or aluminum nitride), and the surface layer 17 may be magnesium fluoride, iridium, aluminum trifluoride, etc., each of which exhibits a favorable surface characteristic when employed as a heater coating within a semiconductor device processing

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chamber. It will be understood that in most instances, the thickness of the intermediate coating, and preferably the thickness of each of the intermediate layers therein, is minimal (i.e., only as thick as is needed to effectively reduce thermal stress). Intermediate coatings of minimal thickness reduce attenuation of the underlying part's favorable characteristics (e.g., heat transfer) and reduce material costs. The intermediate layers 19a-e may be formed by conventional methods (e.g., chemical vapor deposition, physical vapor deposition, plasma spray, diffusion bonding) as will be apparent to those of ordinary skill in the art. (Column 3 lines 66-68; Column 4 lines 1-17)

The motivation for employing coatings that relieve stress is that it allows for employing a variety of coatings for the external coating. (Column 1 lines 5-11)

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have utilized stress relieving layers as taught Bang et al. because it allows for employing a variety of coating for the external coating.

5. Claims 18-27 are rejected under 35 U.S.C. 103(a) as being unpatentable over Michio et al. (Japan 09-272965) in view of Kazuyoshi et al. (Japan 11-345780).

Michio et al. is discussed above and all is as applies above. (See Michio et al. Discussed above) Michio et al. teach the sputtering apparatus with Ti target as seen Figure 3 where components including the target non-erosion portion and backing plate are coated with a peeling preventing film of Ti (See Figure 3) The parameters of the film are discussed above in the discussion of Michio et al.

The difference between Michio et al. and the present claims is that the Rv and Rp values are not discussed and the Vickers hardness is not discussed.

As discussed above Kazuyoshi et al. teach a defect prevention film with the required roughness values. Rz is calculated from Rv and Rp values by JIS B 0601 methods. The range falls within the range of applicants claims. (See Kazuyoshi et al. discussed above)

As to the Vickers Hardness since both Kazuyoshi et al. and Michio et al. teach spray coating a metal such as Titanium it is presumed that such spray process would produce a film having the required Vicker hardness since Applicant utilizes spray coating to produce their film. (See Kazuyoshi et al. and Michio et al. discussed above)

The motivation for applying a film with certain roughness parameters and hardness parameters is that it allows for prevention of film release. (See Kazuyoshi et al. discussed above)

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified Michio et al. by utilizing certain roughness parameters and hardness parameters as taught by Kazuyoshi et al. because it allows for prevention of film release.

Response to Arguments

Applicant's arguments filed January 29, 2003 have been fully considered but they are not 6. persuasive.

RESPONSE TO THE ARGUMENTS OF THE 35 U.S.C. 112 REJECTIONS:

The 35 U.S.C. 112 rejections have been overcome. As to the term "low" in the claims claim 8 does define the level of hardness and thus what is meant by "low hardness".

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RESPONSE TO THE ARGUMENTS OF THE 35 U.S.C. 103 REJECTIONS:

In response to the argument that Kazuyoshi et al. teach away from the present invention because Kazuyoshi et al. suggest going toward higher Rz values and S values whereas Applicant's invention suggests going toward lower Rz and S values, it is argued that Applicant has not shown the desire to choose higher or lower Rz values or S values within Applicant's claimed range.

Applicant has shown in table 4 that either Sample 1 or Sample 5 yield good results with Sample 5 yielding better results than Sample 1. Sample 5 has higher Rz values and S values than Sample 1 which does not necessarily lead to the conclusion that Applicant desires lower Rz values and S values within Applicant's claimed range. Table 4 does suggest that one would want to operate in Applicant's claimed range because lower values (i.e. less than 50 microns see Comparative example 7) lead to poor results. Kazuyoshi et al.'s teaching overlaps Applicant's claimed range and it would be obvious to optimize overlapping ranges to achieve the best results. Therefore, Kazuyoshi et al. do suggest Applicants' required roughnesses. (See Kazuyoshi et al. discussed above)

In response to the argument that the references of Kazuyoshi et al. or Michio et al. do not suggest the hardness and that simply stating that spraying creates a hardness layer comparable to Applicant's layer, it is argued that while Kazuyoshi et al. or Michio et al. do not give a Vickers hardness it is believed that the hardness would be created by the process of spraying. Applicant disagrees with this position and contends that annealing is necessary to achieve the hardness. However it should be noted that Michio et al. teach the process of heat-treating (i.e. annealing) a

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sprayed coating which inherently would create a hardness comparable to Applicant's since the same process and metal is utilized to form the coating. (See Kazuyoshi et al., Michio et al. and Michio et al. Machine Translation)

Conclusion

7. THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

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8. Any inquiry concerning this communication or earlier communications from the examiner

should be directed to Rodney McDonald whose telephone number is 703-308-3807. The

examiner can normally be reached on M-Th from 8 to 5:30. The examiner can also be reached on

alternate Fridays.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor,

Nam X. Nguyen, can be reached on (703) 308-3322. The fax phone number for the organization

where this application or proceeding is assigned is 703-872-9310.

Any inquiry of a general nature or relating to the status of this application or proceeding

should be directed to the receptionist whose telephone number is 703-308-0661.

RODNEY G. MCDONALD

PRIMARY EXAMINER

RM

March 17, 2003